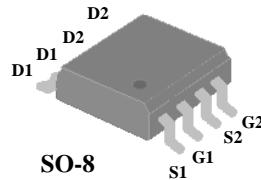




- ▼ Low On-Resistance
- ▼ Capable of 2.5V Gate Drive
- ▼ Dual N MOSFET Package
- ▼ RoHS Compliant & Halogen-Free

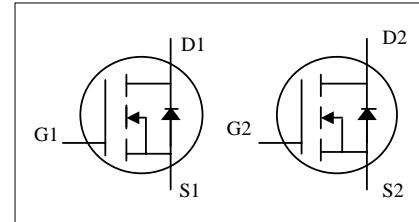


BV _{DSS}	20V
R _{DS(ON)}	14mΩ
I _D	10A

Description

Advanced Power MOSFETs from APEC provide the designer with the best combination of fast switching, ruggedized device design, ultra low on-resistance and cost-effectiveness.

The SO-8 package is widely preferred for commercial-industrial surface mount applications and suited for low voltage applications such as DC/DC converters.



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	20	V
V _{GS}	Gate-Source Voltage	+12	V
I _D @T _A =25°C	Continuous Drain Current ³	10	A
I _D @T _A =70°C	Continuous Drain Current ³	8	A
I _{DM}	Pulsed Drain Current ¹	30	A
P _D @T _A =25°C	Total Power Dissipation	2	W
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Value	Unit
R _{thj-a}	Maximum Thermal Resistance, Junction-ambient ³	62.5	°C/W



Electrical Characteristics@ $T_j=25^\circ\text{C}$ (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV_{DSS}	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=250\mu\text{A}$	20	-	-	V
$\text{R}_{\text{DS(ON)}}$	Static Drain-Source On-Resistance ²	$\text{V}_{\text{GS}}=4.5\text{V}, \text{I}_D=10\text{A}$	-	-	14	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=2.5\text{V}, \text{I}_D=7\text{A}$	-	-	23	$\text{m}\Omega$
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_D=250\mu\text{A}$	0.3	-	1.2	V
g_{fs}	Forward Transconductance	$\text{V}_{\text{DS}}=10\text{V}, \text{I}_D=10\text{A}$	-	16	-	S
I_{DSS}	Drain-Source Leakage Current	$\text{V}_{\text{DS}}=16\text{V}, \text{V}_{\text{GS}}=0\text{V}$	-	-	10	uA
I_{GSS}	Gate-Source Leakage	$\text{V}_{\text{GS}}=\pm 12\text{V}, \text{V}_{\text{DS}}=0\text{V}$	-	-	± 100	nA
Q_{g}	Total Gate Charge	$\text{I}_D=11\text{A}$	-	10	-	nC
Q_{gs}	Gate-Source Charge	$\text{V}_{\text{DS}}=15\text{V}$	-	3	-	nC
Q_{gd}	Gate-Drain ("Miller") Charge	$\text{V}_{\text{GS}}=4.5\text{V}$	-	4.5	-	nC
$\text{t}_{\text{d(on)}}$	Turn-on Delay Time	$\text{V}_{\text{DS}}=15\text{V}$	-	9	-	ns
t_r	Rise Time	$\text{I}_D=1\text{A}$	-	5	-	ns
$\text{t}_{\text{d(off)}}$	Turn-off Delay Time	$\text{R}_G=3.3\Omega$	-	21	-	ns
t_f	Fall Time	$\text{V}_{\text{GS}}=10\text{V}$	-	4.5	-	ns
C_{iss}	Input Capacitance	$\text{V}_{\text{GS}}=0\text{V}$	-	1100	-	pF
C_{oss}	Output Capacitance	$\text{V}_{\text{DS}}=15\text{V}$	-	140	-	pF
C_{rss}	Reverse Transfer Capacitance	f=1.0MHz	-	100	-	pF
R_{g}	Gate Resistance	f=1.0MHz	-	1.3	-	Ω

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V_{SD}	Forward On Voltage ²	$\text{I}_S=1.7\text{A}, \text{V}_{\text{GS}}=0\text{V}$	-	-	1.2	V
t_{rr}	Reverse Recovery Time	$\text{I}_S=11\text{A}, \text{V}_{\text{GS}}=0\text{V},$ $d\text{I}/dt=100\text{A}/\mu\text{s}$	-	17	-	ns
Q_{rr}	Reverse Recovery Charge		-	8	-	nC

Notes:

- 1.Pulse width limited by Max. junction temperature.
- 2.Pulse test
- 3.Surface mounted on 1 in² copper pad of FR4 board ; 135 °C/W when mounted on min. copper pad.

THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

USE OF THIS PRODUCT AS A CRITICAL COMPONENT IN LIFE SUPPORT OR OTHER SIMILAR SYSTEMS IS NOT AUTHORIZED.

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